

# PMEM4020AND

NPN transistor/Schottky rectifier module

Rev. 01 — 4 October 2004

Product data sheet

## 1. Product profile

### 1.1 General description

Combination of an NPN transistor with low  $V_{CEsat}$  and high current capability and a planar Schottky barrier rectifier with an integrated guard ring for stress protection in a SOT457 (SC-74) small plastic package. PNP complement: PMEM4020APD.

### 1.2 Features

- 600 mW total power dissipation
- High current capability up to 2 A
- Reduces printed-circuit board area required
- Reduces pick and place costs
- Small plastic SMD package
- Transistor
  - ◆ Low collector-emitter saturation voltage.
- Diode
  - ◆ Ultra high-speed switching
  - ◆ Very low forward voltage
  - ◆ Guard ring protected.

### 1.3 Applications

- DC-to-DC converters
- Inductive load drivers
- General purpose load drivers
- Reverse polarity protection circuits
- MOSFET drivers.

### 1.4 Quick reference data

Table 1: Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>NPN transistor</b>						
$V_{CEO}$	collector-emitter voltage	open base	-	-	40	V
$I_C$	collector current (DC)	continuous; $T_s \leq 55\text{ °C}$	[1] -	-	2	A

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**Table 1: Quick reference data ...continued**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Schottky barrier rectifier</b>						
$V_R$	continuous reverse voltage		-	-	40	V
$I_F$	continuous forward current		-	-	1	A

[1] Soldering point of collector or cathode tab.

## 2. Pinning information

**Table 2: Discrete pinning**

Pin	Description	Simplified outline	Symbol
1	emitter	<p style="text-align: center;">SOT457</p>	<p style="text-align: center;">sym041</p>
2	not connected		
3	cathode		
4	anode		
5	base		
6	collector		

## 3. Ordering information

**Table 3: Ordering information**

Type number	Package		
	Name	Description	Version
PMEM4020AND	SC-74	plastic surface mounted package; 6 leads	SOT457

## 4. Marking

**Table 4: Marking**

Type number	Marking code
PMEM4020AND	D2

## 5. Limiting values

**Table 5: Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
<b>NPN transistor</b>					
$V_{CBO}$	collector-base voltage	open emitter	-	40	V
$V_{CEO}$	collector-emitter voltage	open base	-	40	V
$V_{EBO}$	emitter-base voltage	open collector	-	5	V

**Table 5: Limiting values ...continued**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$I_C$	collector current (DC)	continuous	[1] -	0.95	A
		continuous	[2] -	1.30	A
		continuous	[3] -	1.65	A
		continuous; $T_s \leq 55\text{ °C}$	[4] -	2	A
$I_{CM}$	peak collector current		-	3	A
$I_{BM}$	peak base current		-	1	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1] -	295	mW
		$T_{amb} \leq 25\text{ °C}$	[2] -	400	mW
		$T_{amb} \leq 25\text{ °C}$	[3] -	500	mW
		$T_s \leq 55\text{ °C}$	[4] -	1000	mW
$T_j$	junction temperature		-	150	°C
<b>Schottky barrier rectifier</b>					
$V_R$	continuous reverse voltage		-	40	V
$I_F$	continuous forward current		-	1	A
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1\text{ ms}; \delta \leq 0.5$	-	3.5	A
$I_{FSM}$	non-repetitive peak forward current	$t = 8\text{ ms};$ square wave	-	10	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1] -	295	mW
		$T_{amb} \leq 25\text{ °C}$	[2] -	400	mW
		$T_{amb} \leq 25\text{ °C}$	[3] -	500	mW
		$T_s \leq 55\text{ °C}$	[4] -	1000	mW
$T_j$	junction temperature		[2] -	150	°C
<b>Combined device</b>					
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2] -	600	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_{amb}$	ambient temperature		[2] -65	+150	°C

[1] Mounted on a FR4 printed-circuit board, single-sided copper, tin-plated, standard footprint.

[2] Device mounted on a printed-circuit board, single-sided copper, tin-plated, 1 cm<sup>2</sup> mounting pad for both collector and cathode.

[3] Mounted on a ceramic printed-circuit board, single-sided copper, tin-plated, standard footprint.

[4] Soldering point of collector or cathode tab.

## 6. Thermal characteristics

Table 6: Thermal characteristics [1]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Single device</b>						
$R_{th(j-s)}$	thermal resistance from junction to soldering point	in free air	[2] -	-	95	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[3] -	-	250	K/W
			[4] -	-	315	K/W
			[5] -	-	425	K/W
<b>Combined device</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[3] -	-	208	K/W

[1] For Schottky barrier rectifiers thermal run-away has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses. Nomograms for determining the reverse power losses  $P_R$  and  $I_{F(AV)}$  rating will be available on request.

[2] Soldering point of collector or cathode tab.

[3] Mounted on a ceramic printed-circuit board, single-sided copper, tin-plated, standard footprint.

[4] Device mounted on a printed-circuit board, single-sided copper, tin-plated, 1 cm<sup>2</sup> mounting pad for both collector and cathode tab.

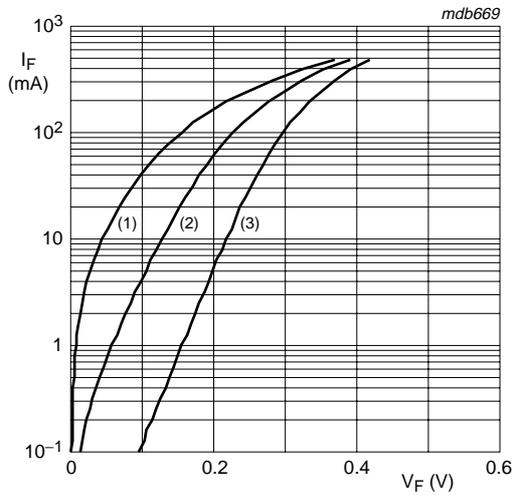
[5] Mounted on a FR4 printed-circuit board, single-sided copper, tin-plated, standard footprint.

## 7. Characteristics

**Table 7: Characteristics**
*T<sub>amb</sub> = 25 °C unless otherwise specified.*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>NPN transistor</b>						
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 40 V; I <sub>E</sub> = 0 A	-	-	100	nA
		V <sub>CB</sub> = 40 V; I <sub>E</sub> = 0 A; T <sub>j</sub> = 150 °C	-	-	50	μA
I <sub>CEO</sub>	collector-emitter cut-off current	V <sub>CE</sub> = 30 V; I <sub>B</sub> = 0 A	-	-	100	nA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = 5 V; I <sub>C</sub> = 0 A	-	-	100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 1 mA	300	-	-	
		V <sub>CE</sub> = 5 V; I <sub>C</sub> = 500 mA	300	-	900	
		V <sub>CE</sub> = 5 V; I <sub>C</sub> = 1 A	200	-	-	
		V <sub>CE</sub> = 5 V; I <sub>C</sub> = 2 A	[1] 75	-	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 100 mA; I <sub>B</sub> = 1 mA	-	-	75	mV
		I <sub>C</sub> = 500 mA; I <sub>B</sub> = 50 mA	-	-	100	mV
		I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA	-	-	190	mV
		I <sub>C</sub> = 2 A; I <sub>B</sub> = 200 mA	-	-	400	mV
R <sub>CEsat</sub>	equivalent on-resistance	I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA	[1] -	150	190	mΩ
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA	[1] -	-	1.2	V
V <sub>BEon</sub>	base-emitter turn-on voltage	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 1 A	[1] -	-	1.1	V
f <sub>T</sub>	transition frequency	V <sub>CE</sub> = 10 V; I <sub>C</sub> = 50 mA; f = 100 MHz	150	-	-	MHz
C <sub>c</sub>	collector capacitance	V <sub>CB</sub> = 10 V; I <sub>E</sub> = i <sub>e</sub> = 0 A; f = 1 MHz	-	-	10	pF
<b>Schottky barrier rectifier</b>						
V <sub>F</sub>	continuous forward voltage	see <a href="#">Figure 1</a>				
		I <sub>F</sub> = 0.1 mA	[1] -	95	130	mV
		I <sub>F</sub> = 1 mA	[1] -	155	210	mV
		I <sub>F</sub> = 10 mA	[1] -	220	270	mV
		I <sub>F</sub> = 100 mA	[1] -	295	350	mV
I <sub>R</sub>	reverse current	see <a href="#">Figure 2</a>				
		V <sub>R</sub> = 10 V	[1] -	7	20	μA
		V <sub>R</sub> = 40 V	[1] -	30	100	μA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; see <a href="#">Figure 3</a>	-	43	48	pF

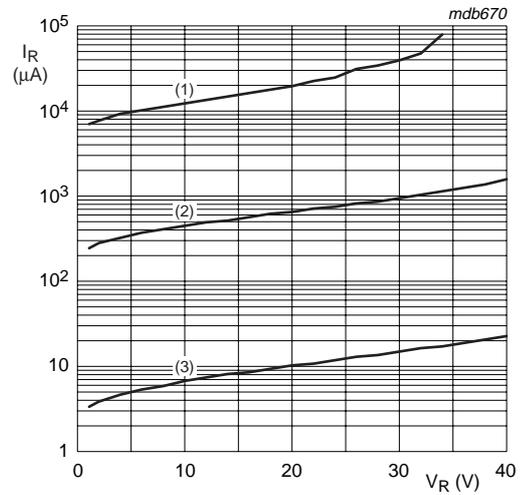
[1] Pulse test: t<sub>p</sub> ≤ 300 μs; δ ≤ 0.02.



Schottky barrier rectifier.

- (1)  $T_{amb} = 150\text{ }^{\circ}\text{C}$ .
- (2)  $T_{amb} = 85\text{ }^{\circ}\text{C}$ .
- (3)  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

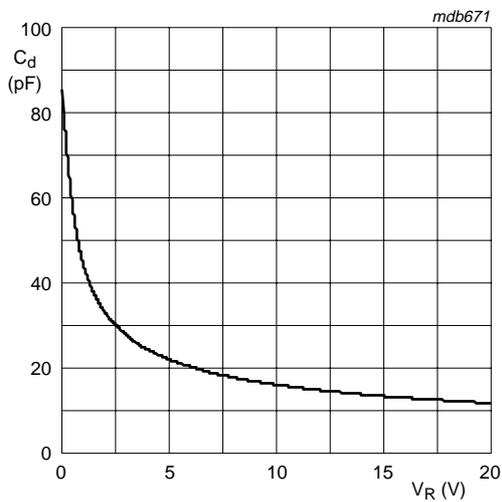
Fig 1. Forward current as a function of forward voltage; typical values.



Schottky barrier rectifier.

- (1)  $T_{amb} = 150\text{ }^{\circ}\text{C}$ .
- (2)  $T_{amb} = 85\text{ }^{\circ}\text{C}$ .
- (3)  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

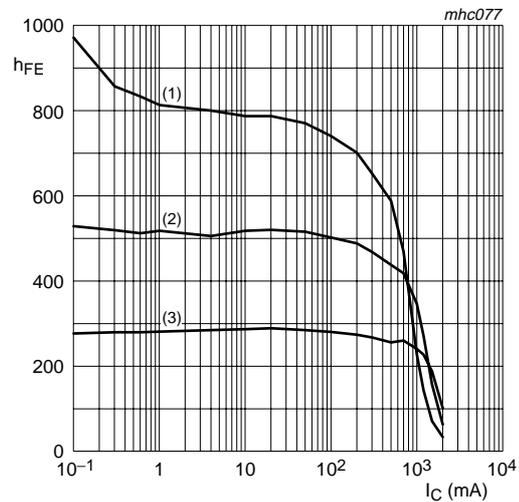
Fig 2. Reverse current as a function of reverse voltage; typical values.



Schottky barrier rectifier;

$T_{amb} = 25\text{ }^{\circ}\text{C}$ ;  $f = 1\text{ MHz}$ .

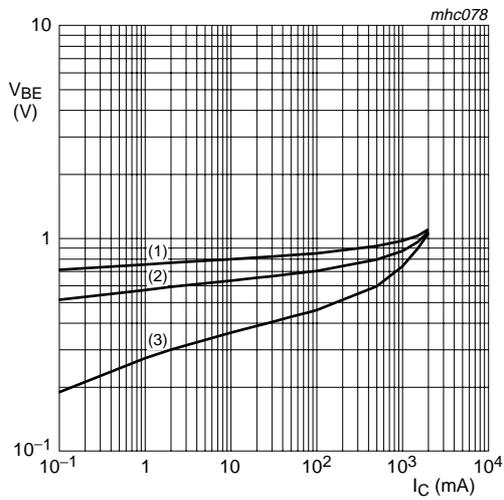
Fig 3. Diode capacitance as a function of reverse voltage; typical values.



NPN transistor;  $V_{CE} = 5\text{ V}$ .

- (1)  $T_{amb} = 150\text{ }^{\circ}\text{C}$ .
- (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .
- (3)  $T_{amb} = -55\text{ }^{\circ}\text{C}$ .

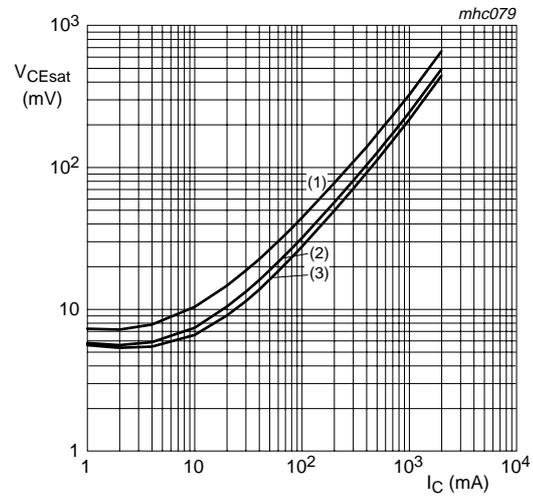
Fig 4. DC current gain as a function of collector current; typical values.



NPN transistor;  $V_{CE} = 5 \text{ V}$ .

- (1)  $T_{amb} = -55 \text{ }^\circ\text{C}$ .
- (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$ .
- (3)  $T_{amb} = 150 \text{ }^\circ\text{C}$ .

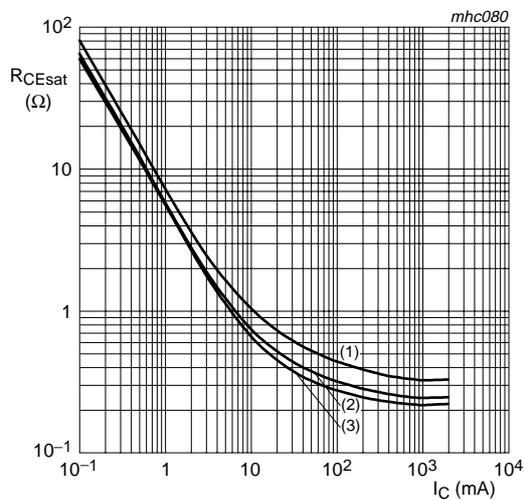
Fig 5. Base-emitter voltage as a function of collector current; typical values.



NPN transistor;  $I_C/I_B = 10$ .

- (1)  $T_{amb} = 150 \text{ }^\circ\text{C}$ .
- (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$ .
- (3)  $T_{amb} = -55 \text{ }^\circ\text{C}$ .

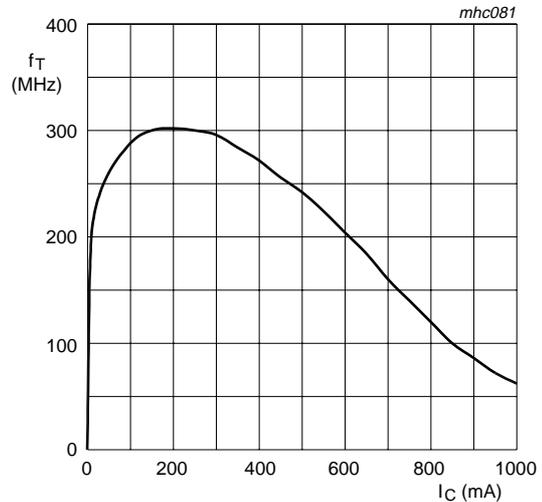
Fig 6. Collector-emitter saturation voltage as a function of collector current; typical values.



NPN transistor;  $I_C/I_B = 10$ .

- (1)  $T_{amb} = 150 \text{ }^\circ\text{C}$ .
- (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$ .
- (3)  $T_{amb} = -55 \text{ }^\circ\text{C}$ .

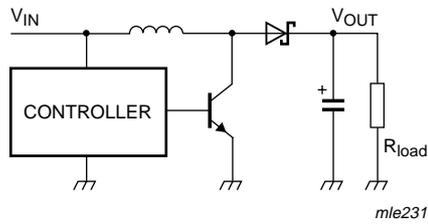
Fig 7. Equivalent on-resistance as a function of collector current; typical values.



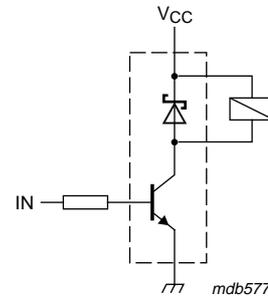
NPN transistor;  $V_{CE} = 10 \text{ V}$ .

Fig 8. Transition frequency as a function of collector current.

## 8. Application information



**Fig 9.** DC-to-DC converter.



**Fig 10.** Inductive load driver (relays, motors and buzzers) with free-wheeling diode.

**9. Package outline**

Plastic surface mounted package; 6 leads

SOT457

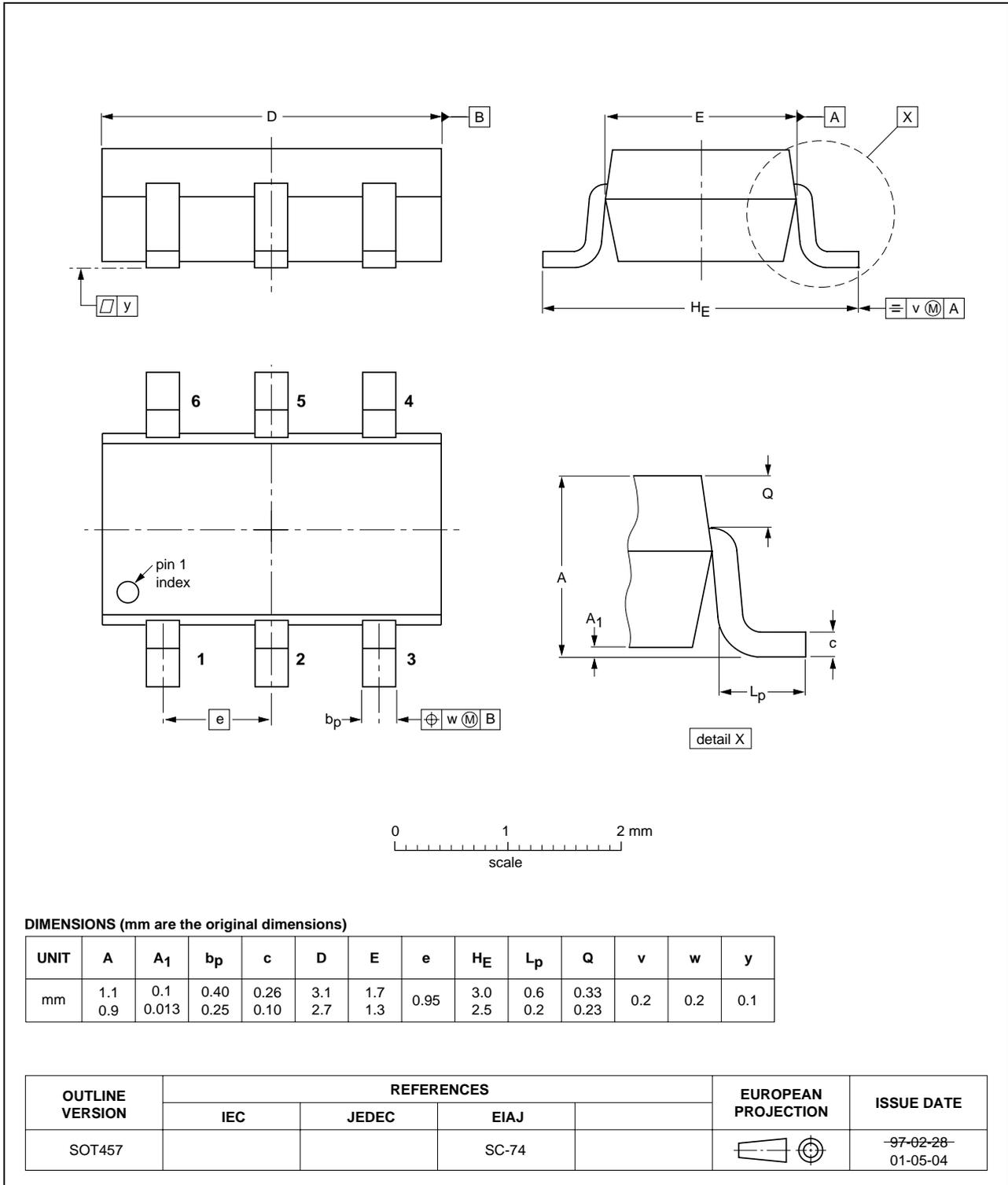


Fig 11. Package outline SOT457 (SC-74).

## 10. Packing information

**Table 8: Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code. [\[1\]](#)

Type number	Package	Description	Packing quantity	
			3000	10000
PMEM4020AND	SOT457	4 mm pitch, 8 mm tape and reel; T1	-115	-135
		4 mm pitch, 8 mm tape and reel; T2	-125	-165

[1] For further information and the availability of packing methods, see [Section 15](#).



## 11. Revision history

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**Table 9: Revision history**

Document ID	Release date	Data sheet status	Change notice	Order number	Supersedes
PMEM4020AND_1	20041004	Product data sheet	-	9397 750 13708	-

## 12. Data sheet status

Level	Data sheet status <sup>[1]</sup>	Product status <sup>[2]</sup> <sup>[3]</sup>	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

## 13. Definitions

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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